

412S Post-CMP Cleaner



The G&P Technology 412S post-CMP cleaning tool is popular with R & D laboratories and start-up organizations who need a high quality, simple to use, single brush box, stand-alone post- CMP wafer cleaning tool . The G & P Technology 412S cleaner can be configured to use the same cleaning consumables-set typically used on integrated CMP planarization tools. This cleaner provides a method for using cleaning recipes similar to those used on full scale integrated production tools. This makes technology transfer seamless and facilitates shorter time-to-market requirements.

FEATURES

- 100mm to 300mm wafer size
- Double-sided PVA brush
- Single wafer load rinse station
- Spin rinse dry output station

OPTIONS

- Megasonic Unit for enhanced cleaning
- Quick dump rinse (QDR-1, single tank)
- Quick dump rinse (QDR-2, recycling)
- Cleaner gripper option



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STANDARD CONFIGURATION - Model 412S	
Wafer size capacity	100mm to 300mm
Cleaning sequence	Single wafer, Manual load
	Pre-cleaning DI H ₂ O rinse
	Double-sided PVA brush
	Spin rinse and dry (SRD)
Number of Brush Stations	1, double-sided PVA
Brush size	70 OD x 32 ID x 170 L
Rotating speed	Up to 200 rpm
Brush position adjustment angle	-10mm to +2mm
Number of chemical inputs	1
Type (typical)	NH ₄ OH
Chemical supply	2 spray nozzles and through the brush
Spin Station rotational speed	Up to 2000 rpm
Spin station rinse	DI H ₂ O
Blow off/Drying method	N ₂ blow off
Operator interface	Intuitive touch screen
Cleaning time (typical)	3 minutes per wafer

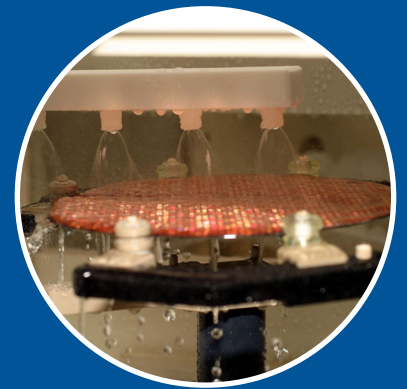
OPTIONS AVAILABLE	
Megasonic Unit	For enhanced cleaning action
Quick Dump Rinse (QDR-1)	Simple tank type
Quick Dump Rinse (QDR-2)	Recycling type
Cleaner Gripper option	4, 6, 8, 12 inch

DIMENSIONS		
Metric	1000W x 835D x 1250H	
Inches	40W x 33D x 50H	
Weight	~225 kg	~ 500 lbs

Double-sided PVA brush



Single Wafer Load
Input Rinse Station



Spin Rinse Dry Output Station

